The three-day Exposition is an integral part of the ITSC 2010. If you are looking for new products and services, if you have questions or need answers, the ITSC 2010 Exposition is the right place for you.

The exhibitors are experts who can offer visitors a wealth of problem-solving information and cost-saving opportunities.

You will find information about equipment for thermal spraying, research and specialist institutes, applied research, the latest innovations and, most importantly, they are all together in a big forum where you will find answers to all your questions.

The exhibition will be held in the Raffles City Convention Centre, Collyer & Padang Room with an area of nearly 1,500 sqm gross.

The dates and opening hours of the exposition are planned as follows:

- Monday May 3, 2010
  (from 12:30 pm to 5:00 pm)
- Tuesday May 4 and Wednesday May 5, 2010
  (from 9:00 am to 5:00 pm)

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Call for Papers

ITSC 2010. For more information please contact:

ASM Thermal Spray Society is the Exposition partner for ITSC 2010. For more information please contact:

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Welcome to the 2010 Thermal Spray Conference and Exposition, ITSC is an opportunity for the global thermal spray community to meet, exchange information and conduct business. This outstanding annual event in the world of thermal spray technology is jointly organized by the German Welding Society (DVS), the ASM Thermal Spray Society (TSS) and the International Institute of Welding (IIW). ITSC 2010-as the successful path of the previous events in Beijing (2007), Maastricht (2008) and Las Vegas (2009). It presents the latest state-of-the-art application, research and development in the field of thermal spray.

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* Thermal Spray and other Surface Engineering Technologies

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* Process Diagnostics, Sensors and Controls
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* Pre-Treatment and Post-Treatment
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Abstract Submission
Interested authors are invited to submit their abstracts.
Please use the ITSC 2010 online service to submit your abstracts for oral and poster presentations to www.dvs-ev.de/itsc2010

Interested authors should submit their abstract of 200 words or less in English by August 31, 2009
The submitted abstracts will be reviewed and selected by the Program Committee.
Please notice: All paper/poster manuscripts must be written in English and submitted electronically.
The manuscript deadline for paper and poster contributions will be December 04, 2009
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